

# CD4017B, CD4022B Types

## CMOS Counter/Dividers

High-Voltage Types (20-Volt Rating)

CD4017B—Decade Counter with  
10 Decoded Outputs

CD4022B—Octal Counter with  
8 Decoded Outputs

■ CD4017B and CD4022B are 5-stage and 4-stage Johnson counters having 10 and 8 decoded outputs, respectively. Inputs include a CLOCK, a RESET, and a CLOCK INHIBIT signal. Schmitt trigger action in the CLOCK input circuit provides pulse shaping that allows unlimited clock input pulse rise and fall times.

These counters are advanced one count at the positive clock signal transition if the CLOCK INHIBIT signal is low. Counter advancement via the clock line is inhibited when the CLOCK INHIBIT signal is high. A high RESET signal clears the counter to its zero count. Use of the Johnson counter configuration permits high-speed operation, 2-input decode-gating and spike-free decoded outputs. Anti-lock gating is provided, thus assuring proper counting sequence. The decoded outputs are normally low and go high only at their respective decoded time slot. Each decoded output remains high for one full clock cycle. A CARRY-OUT signal completes one cycle every 10 clock input cycles in the CD4017B or every 8 clock input cycles in the CD4022B and is used to

### Features:

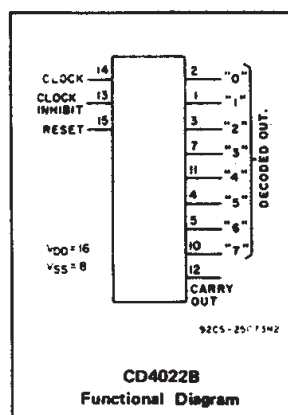
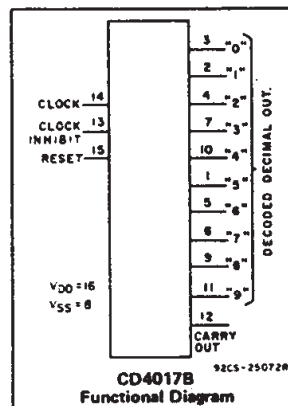
- Fully static operation
- Medium-speed operation . . . 10 MHz (typ.) at  $V_{DD} = 10\text{ V}$
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13A, "Standard Specifications for Description of 'B' Series CMOS Devices"

### Applications:

- Decade counter/decimal decode display (CD4017B)
- Binary counter/decoder
- Frequency division
- Counter control/timers
- Divide-by-N counting
- For further application information, see ICAN-6166 "COS/MOS MSI Counter and Register Design and Applications"

ripple-clock the succeeding device in a multi-device counting chain.

The CD4017B and CD4022B-series types are supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic package (E suffix), 16-lead ceramic flat packages (K suffix), and in chip form (H suffix).

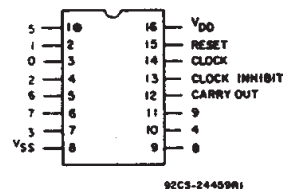


### RECOMMENDED OPERATING CONDITIONS

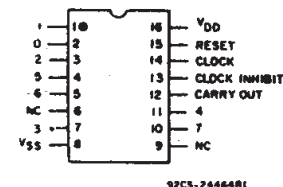
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTICS	$V_{DD}$ (V)	LIMITS		UNITS
		Min.	Max.	
Supply-Voltage Range (For $T_A$ = Full Package-Temperature Range)		3	18	V
Clock Input Frequency, $f_{CL}$	5	—	2.5	MHz
	10	—	5	
	15	—	5.5	
Clock Pulse Width, $t_W$	5	200	—	ns
	10	90	—	
	15	60	—	
Clock Rise & Fall Time, $t_{rCL}$ , $t_{fCL}$	5	UNLIMITED*		
	10			
	15			
Clock Inhibit Setup Time, $t_s$	5	230	—	ns
	10	100	—	
	15	70	—	
Reset Pulse Width, $t_{RW}$	5	260	—	ns
	10	110	—	
	15	60	—	
Reset Removal Time, $t_{rem}$	5	400	—	ns
	10	280	—	
	15	150	—	

\*Only if Pin 14 is used as the clock input. If Pin 13 is used as the clock input and Pin 14 is tied high (for advancing count on negative transition of the clock), rise and fall time should be  $\leq 15\ \mu\text{s}$ .



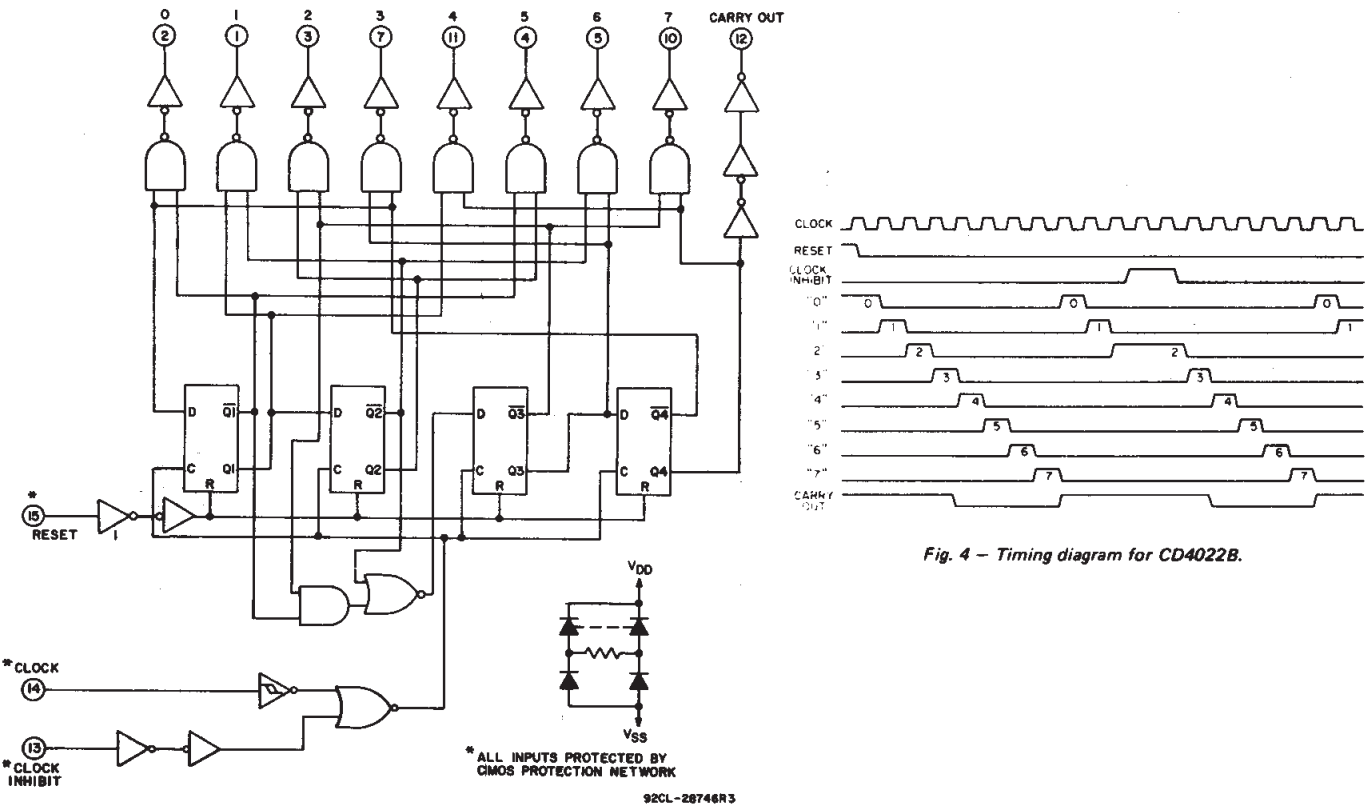
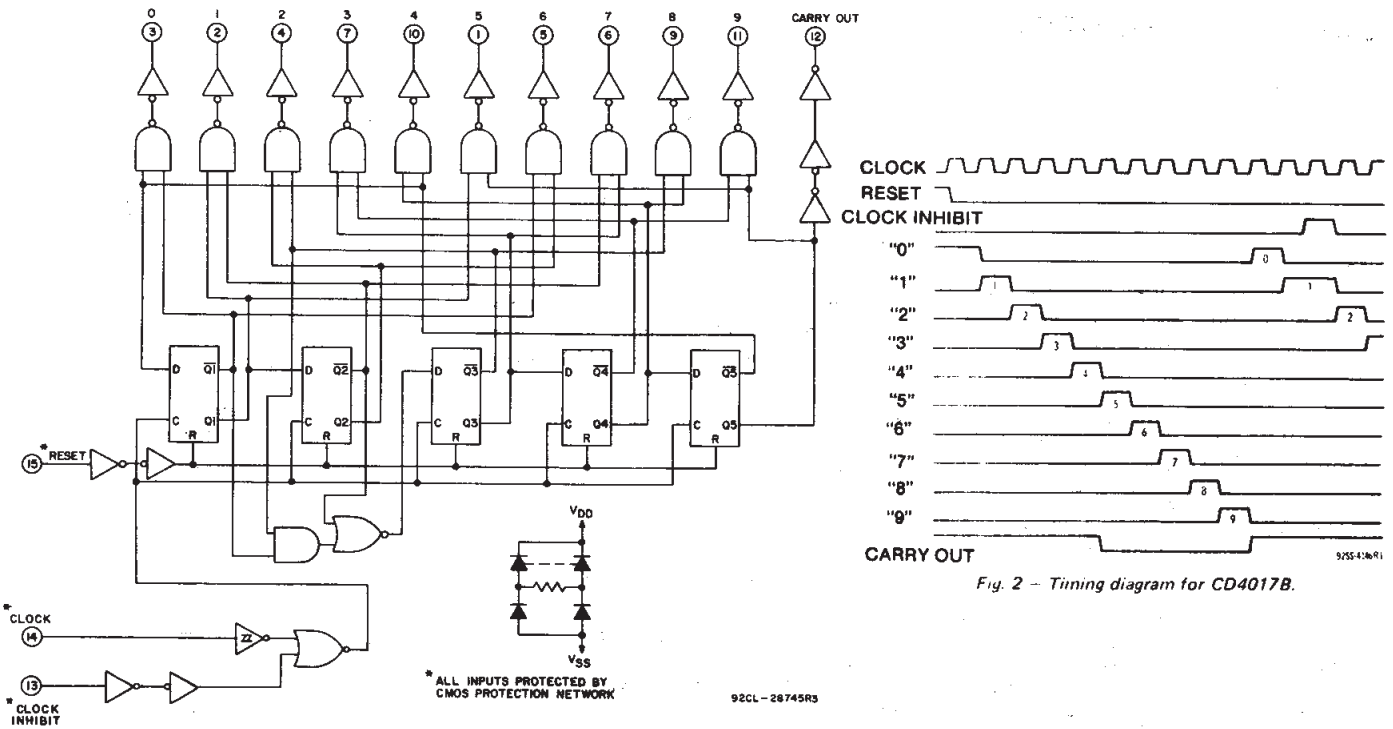
TOP VIEW  
CD4017B  
TERMINAL DIAGRAM



TOP VIEW  
NC - no connection  
CD4022B  
TERMINAL DIAGRAM

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**MAXIMUM RATINGS, Absolute-Maximum Values:**

DC SUPPLY-VOLTAGE RANGE, (V <sub>DD</sub> )	-0.5V to +20V
Voltages referenced to V <sub>SS</sub> Terminal)	
INPUT VOLTAGE RANGE, ALL INPUTS	-0.5V to V <sub>DD</sub> +0.5V
DC INPUT CURRENT, ANY ONE INPUT	±10mA
POWER DISSIPATION PER PACKAGE (P <sub>D</sub> ):	
For T <sub>A</sub> = -55°C to +100°C	500mW
For T <sub>A</sub> = +100°C to +125°C	Derate Linearly at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
FOR T <sub>A</sub> = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	100mW
OPERATING-TEMPERATURE RANGE (T <sub>A</sub> )	-55°C to +125°C
STORAGE TEMPERATURE RANGE (T <sub>stg</sub> )	-65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):	
At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max	+265°C

**STATIC ELECTRICAL CHARACTERISTICS**

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V <sub>O</sub> (V)	V <sub>IN</sub> (V)	V <sub>DD</sub> (V)	-55	-40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I <sub>DD</sub> Max.	-	0.5	5	5	5	150	150	-	0.04	5	μA
	-	0.10	10	10	10	300	300	-	0.04	10	
	-	0.15	15	20	20	600	600	-	0.04	20	
	-	0.20	20	100	100	3000	3000	-	0.08	100	
Output Low (Sink) Current I <sub>OL</sub> Min.	0.4	0.5	5	0.64	0.61	0.42	0.36	0.51	1	-	mA
	0.5	0.10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
	1.5	0.15	15	4.2	4	2.8	2.4	3.4	6.8	-	
Output High (Source) Current, I <sub>OH</sub> Min.	4.6	0.5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mA
	2.5	0.5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	
	9.5	0.10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
	13.5	0.15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage: Low-Level, V <sub>OL</sub> Max.	-	0.5	5	0.05				-	0	0.05	V
	-	0.10	10	0.05				-	0	0.05	
	-	0.15	15	0.05				-	0	0.05	
Output Voltage: High-Level, V <sub>OH</sub> Min.	-	0.5	5	4.95				4.95	5	-	V
	-	0.10	10	9.95				9.95	10	-	
	-	0.15	15	14.95				14.95	15	-	
Input Low Voltage V <sub>IL</sub> Max.	0.5, 4.5	-	5	1.5				-	-	1.5	V
	1.9	-	10	3				-	-	3	
	1.5, 13.5	-	15	4				-	-	4	
Input High Voltage, V <sub>IH</sub> Min.	0.5, 4.5	-	5	3.5				3.5	-	-	V
	1.9	-	10	7				7	-	-	
	1.5, 13.5	-	15	11				11	-	-	
Input Current I <sub>IN</sub> Max.	-	0.18	18	±0.1	±0.1	±1	±1	-	±10 <sup>-5</sup>	±0.1	μA

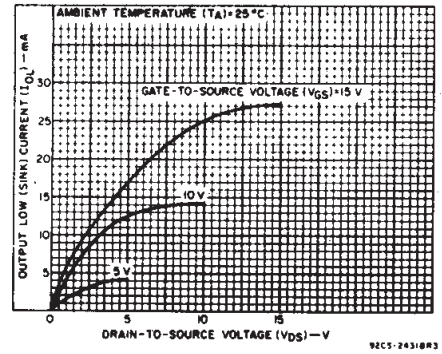


Fig. 5— Typical output low (sink) current characteristics.

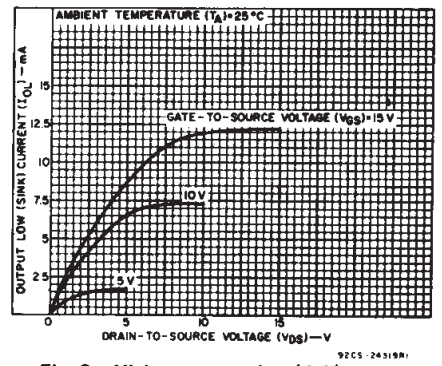


Fig. 6— Minimum output low (sink) current characteristics.

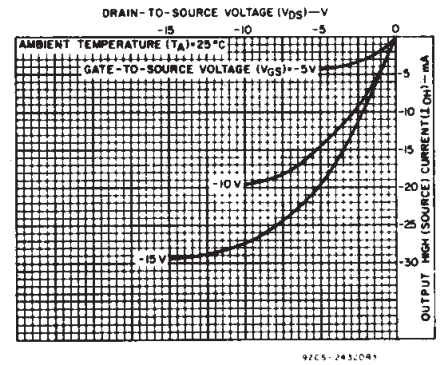


Fig. 7— Typical output high (source) current characteristics.

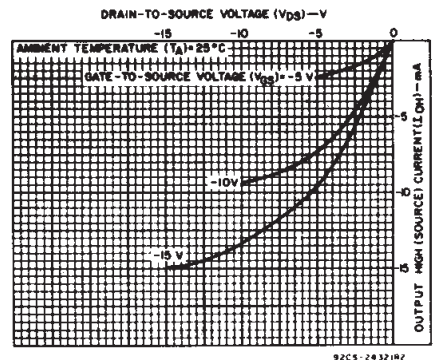


Fig. 8— Minimum output high (source) current characteristics.

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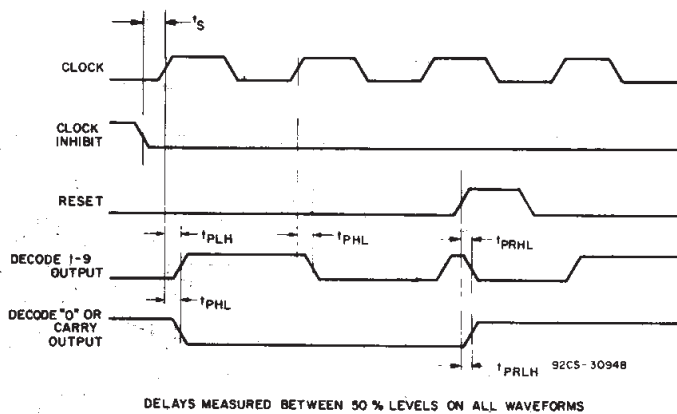
# CD4017B, CD4022B Types

## DYNAMIC ELECTRICAL CHARACTERISTICS

At  $T_A = 25^\circ\text{C}$ , Input  $t_r, t_f = 20 \text{ ns}$ ,  $C_L = 50 \text{ pF}$ ,  $R_L = 200 \text{ k}\Omega$

CHARACTERISTIC	CONDITIONS $V_{DD}$ (V)	LIMITS			UNITS
		Min.	Typ.	Max.	
<b>CLOCKED OPERATION</b>					
Propagation Delay Time, $t_{PHL}, t_{PLH}$ Decode Out	5	—	325	650	ns
	10	—	135	270	
	15	—	85	170	
Carry Out	5	—	300	600	ns
	10	—	125	250	
	15	—	80	160	
Transition Time, $t_{THL}, t_{TLH}$ Carry Out or Decode Out Line	5	—	100	200	ns
	10	—	50	100	
	15	—	40	80	
Maximum Clock Input Frequency, $f_{CL}^*$	5	2.5	5	—	MHz
	10	5	10	—	
	15	5.5	11	—	
Minimum Clock Pulse Width, $t_W$	5	—	100	200	ns
	10	—	45	90	
	15	—	30	60	
Clock Rise or Fall Time, $t_r, t_f$	5, 10, 15	UNLIMITED			
Minimum Clock Inhibit to Clock Setup Time, $t_s$	5	—	115	230	ns
	10	—	50	100	
	15	—	35	70	
Input Capacitance, $C_{IN}$	Any Input	—	5	—	pF
<b>RESET OPERATION</b>					
Propagation Delay Time, $t_{PHL}, t_{PLH}$ Carry Out or Decode Out Lines	5	—	265	530	ns
	10	—	115	230	
	15	—	85	170	
Minimum Reset Pulse Width, $t_W$	5	—	130	260	ns
	10	—	55	110	
	15	—	30	60	
Minimum Reset Removal Time	5	—	200	400	ns
	10	—	140	280	
	15	—	75	150	

\* Measured with respect to carry output line.



DELAYS MEASURED BETWEEN 50% LEVELS ON ALL WAVEFORMS

Fig. 9 - Propagation delay, setup, and reset removal time waveforms.

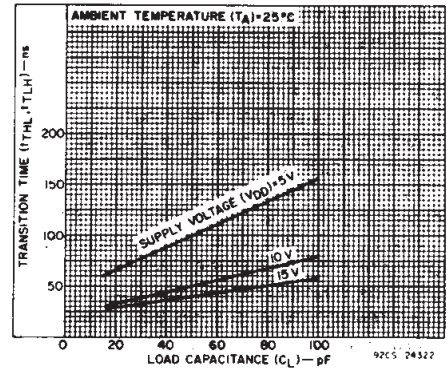


Fig. 10 - Typical transition time as a function of load capacitance.

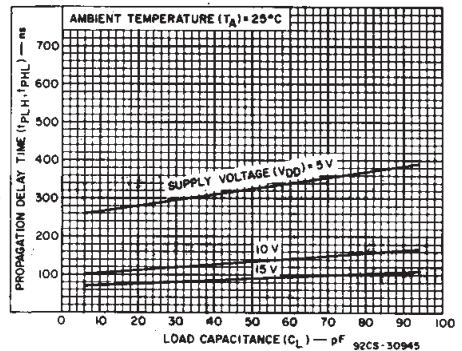


Fig. 11 - Typical propagation delay time as a function of load capacitance (clock to decode output).

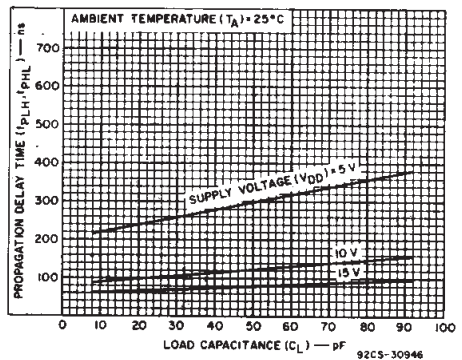


Fig. 12 - Typical propagation delay time as a function of load capacitance (clock to carry-out).

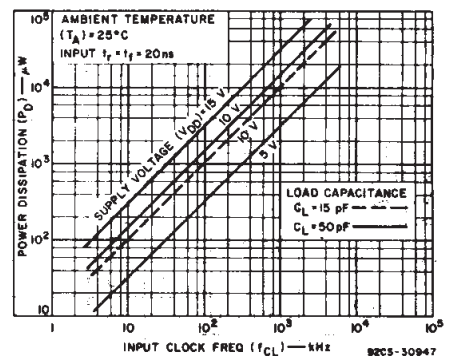


Fig. 13 - Typical dynamic power dissipation as a function of clock input frequency.

# CD4017B, CD4022B Types

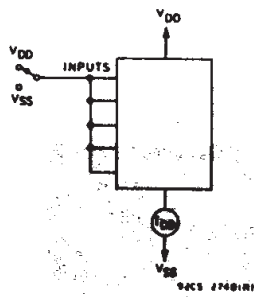


Fig. 14 - Quiescent device-current test circuit.

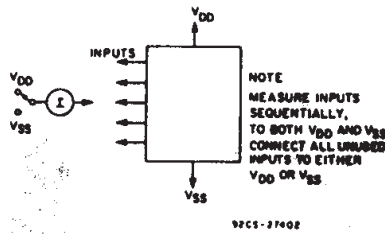


Fig. 15 - Input-leakage current.

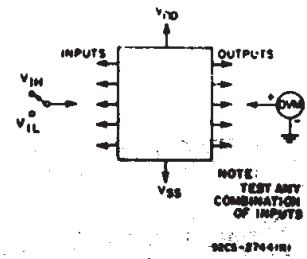


Fig. 16 - Input-voltage test circuit.

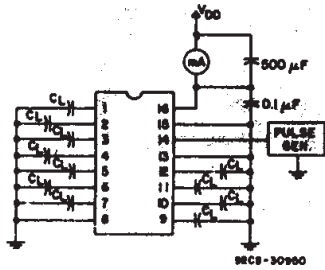


Fig. 17 - Dynamic power dissipation test circuit.

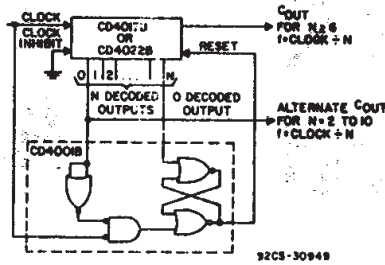


Fig. 18 - Divide by  $N$  counter ( $N \leq 10$ ) with  $N$  decoded outputs.

When the  $N^{\text{th}}$  decoded output is reached ( $N^{\text{th}}$  clock pulse) the S-R flip flop (constructed from two NOR gates of the CD4001B) generates a reset pulse which clears the CD4017B or CD4022B to its zero count. At this time, if the  $N^{\text{th}}$  decoded output is greater than or equal to 6 in the CD4017B or 5 in the CD4022B; the  $C_{\text{OUT}}$  line goes high to clock the next CD4017B or CD4022B counter section. The "0" decoded output also goes high at this time. Coincidence of the clock low and decoded "0" output low resets the S-R flip flop to enable the CD4017B or CD4022B. If the  $N^{\text{th}}$  decoded output is less than 6 (CD4017B) or 5 (CD4022B), the  $C_{\text{OUT}}$  line will not go high and, therefore, cannot be used. In this case "0" decoded output may be used to perform the clocking function for the next counter.

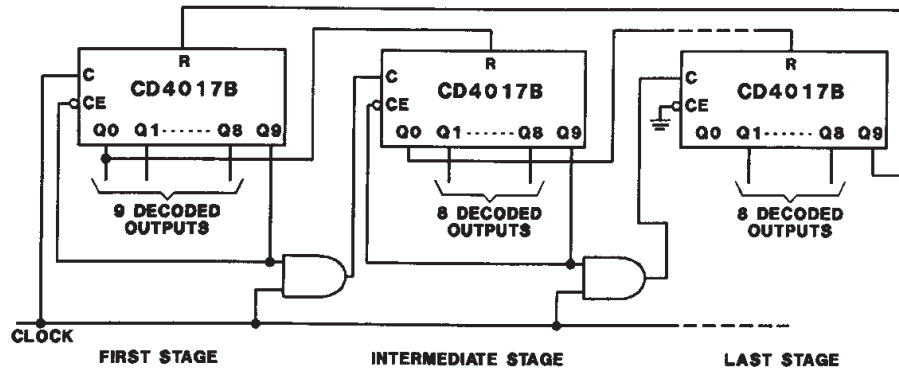
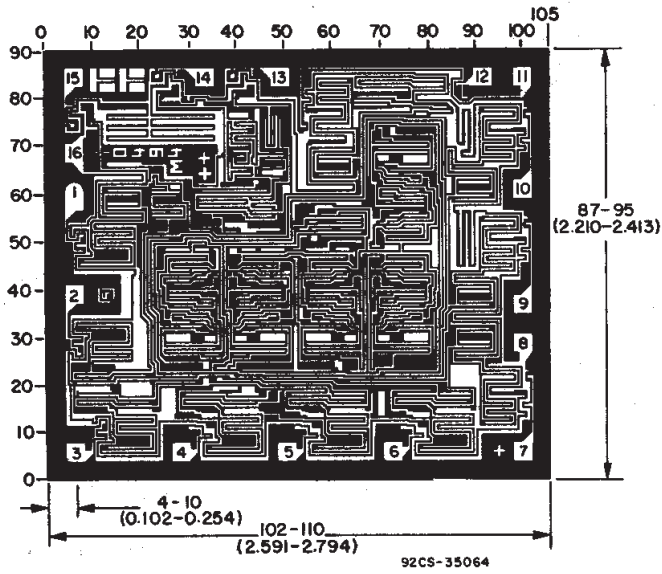


Fig. 19 - Cascading the CD4017B.

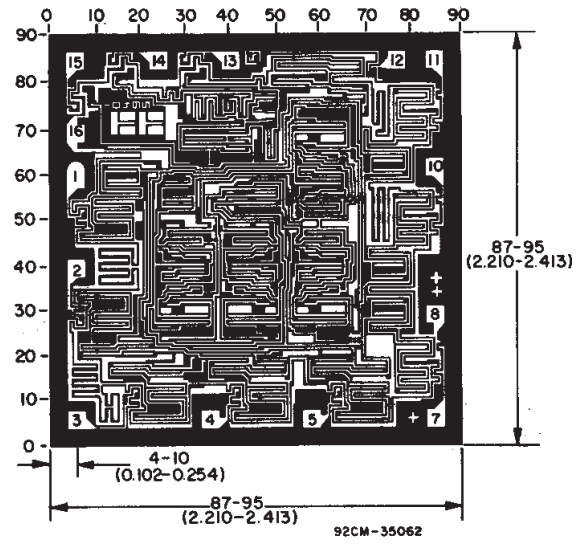
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## CHIP DIMENSIONS AND PAD LAYOUTS



CD4017BH



CD4022BH

*Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils ( $10^{-3}$  inch).*

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